Product/Process Change Notice - PCN 22_0259 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Notification of qualification of additional assembly location ASE Korea for LTM4623.

Publication Date: 19-Oct-2022

Effectivity Date: 21-Jan-2023 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release: Notification of qualification of additional assembly location ASE Korea for LTM4623.

Description Of Change:

ADI is adding ASE Korea as an alternate assembly facility for LTM4623

Reason For Change:

To qualify ASE Korea as an alternate assembly site to ensure the continuous availability of a reliable source of product supply.

Impact of the change (positive or negative) on fit, form, function & reliability:

This change will not impact fit, form, function, and reliability.

Product Identification *(this section will describe how to identify the changed material)*

New products will be identified by the date code.

Summary of Supporting Information:

The qualification has been performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_22_0259_Rev_-_LTM4623 BGA at ASE Korea Qualification Results Summary_PCN Rel data.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.			
Americas: PCN_Americas@analog.com	**Europe:** PCN_Europe@analog.com	**Japan:** PCN_Japan@analog.com	**Rest of Asia:** PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (5)				
LTM4623 / LTM4623EV#PBF	LTM4623 / LTM4623EY#PBF	LTM4623 / LTM4623IV#PBF	LTM4623 / LTM4623IY	LTM4623 / LTM4623IY#PBF

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	19-Oct-2022	21-Jan-2023	Initial Release: Notification of qualification of additional assembly location ASE Korea for LTM4623.

LTM4623 BGA at ASE Korea Qualification Results Summary

Test Name	Specification	Conditions	Device	Sample Size (Lot X samples)	Result
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	LTM4623	1 x 50	Pass
Temperature Cycling (TC) [1]	JESD22-A104	-55°C/+125°C, 1,000 Cycles	LTM4623	1 x 77	Pass
Thermal Shock (TS) [1]	JESD22-A106	-55°C/+125°C, 1,000 Cycles	LTM4623	1 x 77	Pass
Unbiased HAST (UHST) [1]	JESD22-A118	110C 85%RH 17.7 psia, P264	LTM4623	1 x 77	Pass

[1] These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 48 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.